

SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAYS
Features

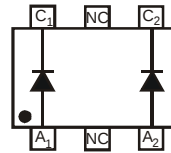
- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free by Design/RoHS Compliant (Note 1)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **"Green" Device (Notes 4 and 5)**



Top View



Bottom View



Device Schematic

Mechanical Data

- Case: SOT-563, Molded Plastic
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Terminals: Lead Bearing Terminal Plating available.
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.003 grams (approximate)

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Forward Continuous Current (Note 2)	I _F	200	mA
Repetitive Peak Forward Current (Note 2)	I _{FRM}	350	mA
Forward Surge Current (Note 2) @ t _p = 10ms	I _{FSM}	750	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P _D	150	mW
Thermal Resistance, Junction to Ambient Air (Note 2)	R _{θJA}	833	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +125	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 3)	V _{(BR)R}	40	—	—	V	I _R = 100μA
Forward Voltage	V _F	—	—	330 420 800 1000	mV	I _F = 2.0mA I _F = 15mA I _F = 100mA I _F = 200mA
Reverse Leakage Current (Note 3)	I _R	—	—	500	nA	V _R = 25V
Total Capacitance	C _T	—	—	10	pF	V _R = 1.0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	5.0	ns	I _F = 10mA through I _R = 10mA to I _R = 1.0mA, R _L = 100Ω

- Notes:
1. No purposefully added lead.
 2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>. T_A = 25°C.
 3. Short duration pulse test used to minimize self-heating effect.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

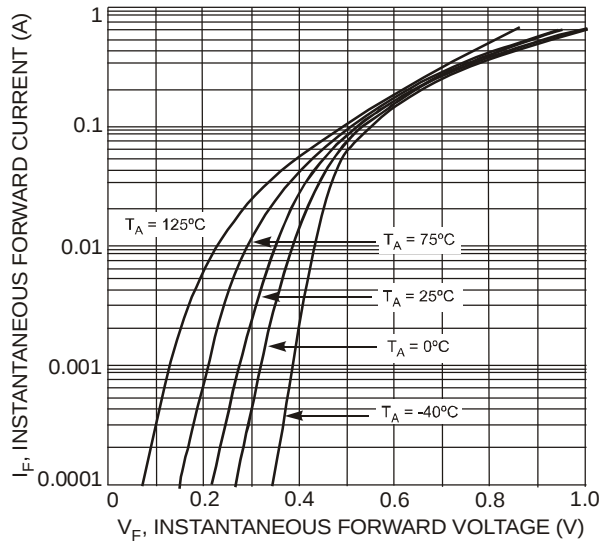


Fig. 1 Typical Forward Characteristics

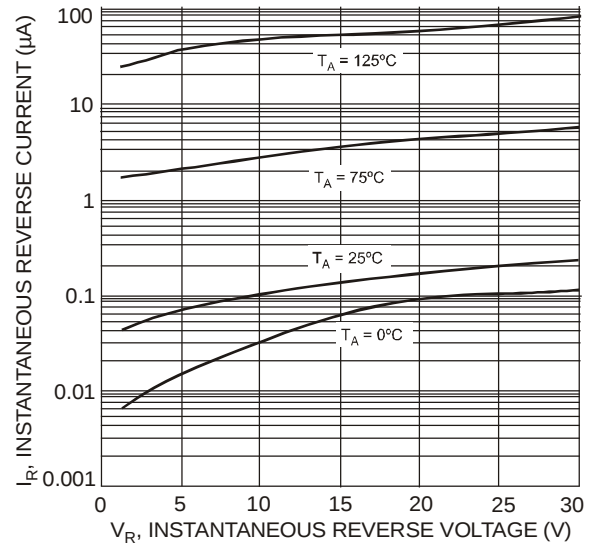


Fig. 2 Typical Reverse Characteristics

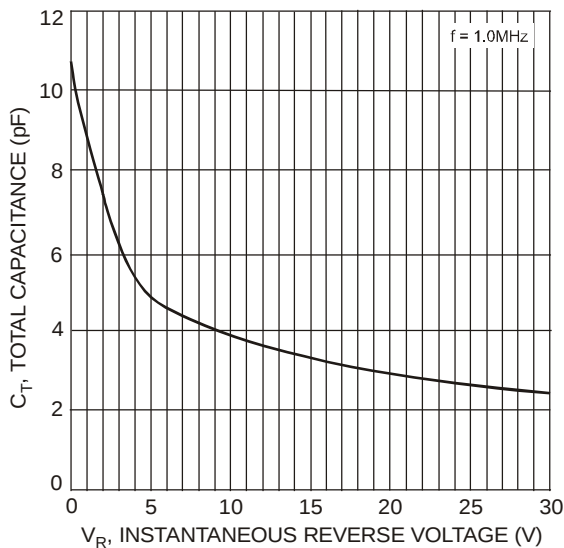


Fig. 3 Total Capacitance vs. Reverse Voltage

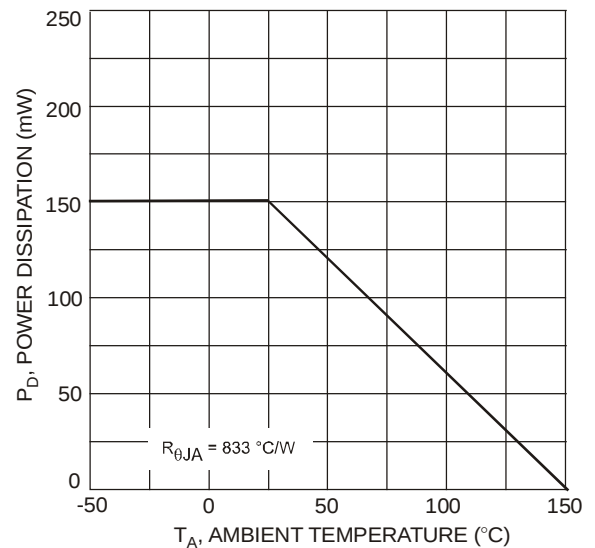


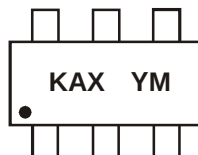
Fig. 4 Derating Curve - Total

Ordering Information (Note 6)

Part Number	Case	Packaging
BAT40V-7	SOT-563	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

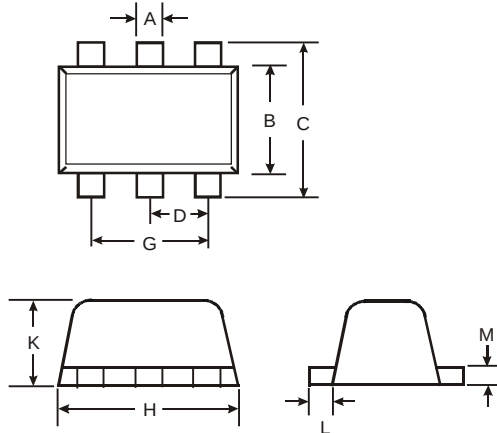


KAX = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: R = 2004)
 M = Month (ex: 9 = September)

Date Code Key

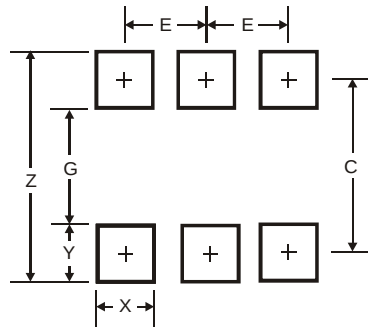
Year	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C	1.7
E	0.5

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